



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3BR0665J		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000981102						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		557.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.709	1.02	1.02	10236	10236
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7705	
wire	non noble metal	copper	7440-50-8	174.475	31.28	32.10	312838	321024
	noble metal	gold	7440-57-5	0.280	0.05	0.05	502	502
	encapsulation	organic material	carbon black	1333-86-4	1.086	0.19		1948
encapsulation	plastics	epoxy resin	-	35.130	6.30		62989	
	inorganic material	silicondioxide	60676-86-0	325.947	58.46	64.95	584432	649369
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13440	13440
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1427	1427
glue	plastics	epoxy resin	-	0.335	0.06		600	
	noble metal	silver	7440-22-4	1.898	0.34	0.40	3402	4002
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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